**Product data sheet** 

## **1 Product profile**

### 1.1 General description

General-purpose pin diode in an SOD323 small plastic SMD package.

### **1.2 Features and benefits**

- Low diode capacitance: maximum 1.05 pF
- Low diode forward resistance: max. 0.7  $\boldsymbol{\Omega}$
- AEC-Q101 qualified

### 1.3 Applications

General RF applications



# 2 Pinning information

Pin	Description	Simplified outline	Graphic symbol
1	cathode		
2	anode		- <del>K]</del> - sym006
		Top view	

# **3** Ordering information

#### Table 2. Ordering information

Type number	Package	Package				
	Name	Description	Version			
BAP51-03	-	plastic surface-mounted package; 2 leads	SOD323			

# 4 Marking

Table 3. Marking code	
Type number	Marking code
BAP51-03	A5 <sup>[1]</sup>

[1] The marking bar indicates the cathode (see simplified outline graphic in <u>Table 1</u>).

## **5** Limiting values

#### Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>R</sub>	continuous reverse voltage		-	50	V
l <sub>F</sub>	continuous forward current		-	50	mA
P <sub>tot</sub>	total power dissipation	T <sub>sp</sub> ≤ 90 °C	-	500	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-65	+150	°C

## **6** Thermal characteristics

#### Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit		
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		120	K/W		

### 7 Characteristics

#### Table 6. Characteristics

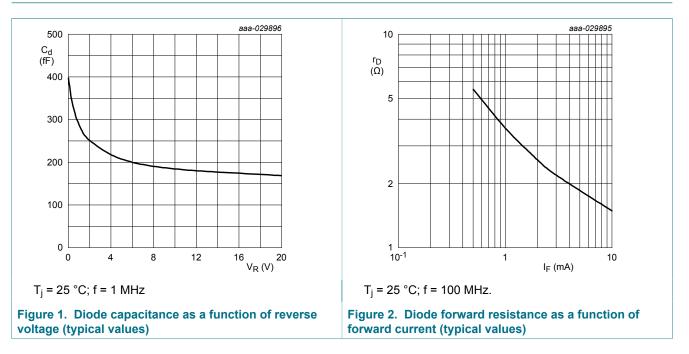
 $T_i = 25$  °C unless otherwise specified.

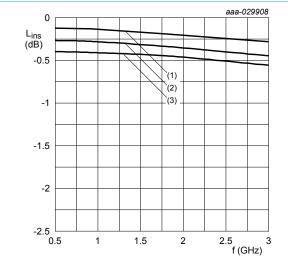
Symbol	Parameter	Conditions	Min	Тур	Мах	Unit	
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 50 mA	-	0.95	1.1	V	
V <sub>R</sub>	reverse voltage	I <sub>R</sub> = 10 μA	50	-	-	V	
I <sub>R</sub>	reverse current	V <sub>R</sub> = 50 V	-	-	100	nA	
C <sub>d</sub>	diode capacitance	f = 1 MHz (see <u>Figure 1</u> )					
		V <sub>R</sub> = 0 V	-	0.4	-	pF	
		V <sub>R</sub> = 1 V	-	0.3	0.55	pF	
		V <sub>R</sub> = 5 V	-	0.2	0.35	pF	
r <sub>D</sub>	diode forward resistance	f = 100 MHz (see <u>Figure 2</u> )					
		I <sub>F</sub> = 0.5 mA	[1] _	5.5	9	Ω	
		I <sub>F</sub> = 1 mA	[1] _	3.6	6.5	Ω	
		I <sub>F</sub> = 10 mA	[1] _	1.5	2.5	Ω	
τι	charge carrier life time	when switched from $I_F = 10 \text{ mA}$ to $I_R = 6 \text{ mA}$ ; $R_L = 100 \Omega$ ; measured at $I_R = 3 \text{ mA}$	-	550	-	ns	

[1] Guaranteed on AQL basis; inspection level S4, AQL 1.0

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### 8 Graphical data



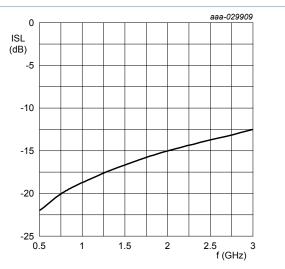


Diode inserted in series with a 50  $\Omega$  strip line circuit and biased via the analyzer T-network; T<sub>amb</sub> = 25 °C

(1) I<sub>F</sub> = 10 mA (2) I<sub>F</sub> = 1 mA

(3) I<sub>F</sub> = 0.5 mA

Figure 3. Insertion loss of the diode as a function of frequency (typical values)

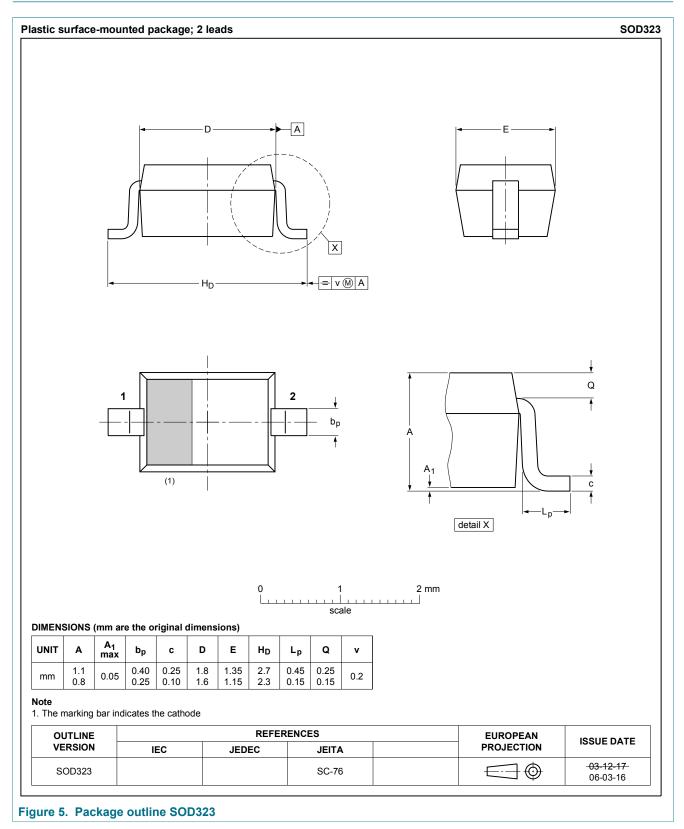


Diode zero-biased and inserted in series with a 50  $\Omega$  strip line circuit and biased via the analyzer T-network; T<sub>amb</sub> = 25 °C; f = 100 MHz

Figure 4. Isolation of the diode as a function of frequency (typical values)

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## 9 Package outline



# **10 Revision history**

Table 7. Revision history					
Document ID	Release date	Data sheet status	Change notice	Supersedes	
BAP51-03 v.5	20181126	Product data sheet	-	BAP51-03 v.3.1	
Modifications:	<u>Section 1.2</u> "Feat	<ul> <li>AEC-Q101 qualification added to the features and benefits</li> <li><u>Section 1.2</u> "Features and benefits" has been updated.</li> <li>The "Legal information" pages have been updated to automotive version</li> </ul>			
BAP51-03 v.4.1	20040211	Product data sheet	-	-	

## **11 Legal information**

### 11.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

Please consult the most recently issued document before initiating or completing a design. [1]

[2] [3] The term 'short data sheet' is explained in section "Definitions".

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# BAP51-03 Band-switching mode

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Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

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